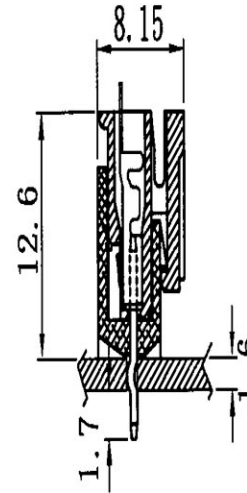
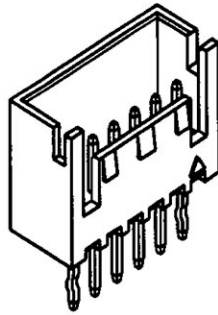
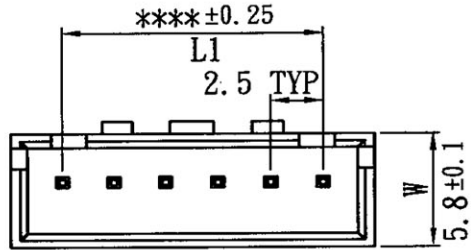


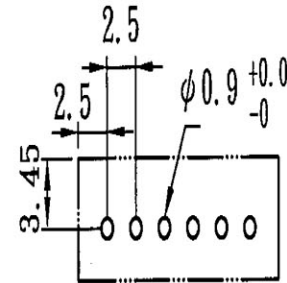
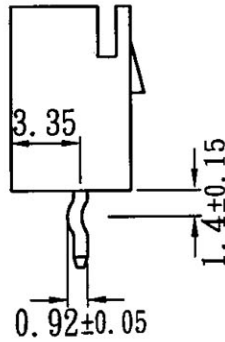
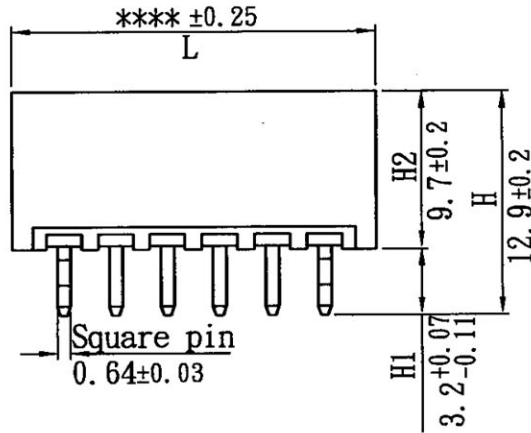
Wafer (2.5mm Pitch Series)

A



B

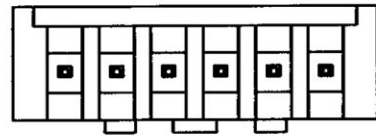
C



D

E

F



Part NO.	Dimension		Q'ty/bag
	L1	L	
2	2.5	7.5	1000 PCS
3	5.0	10.0	1000 PCS
4	7.5	12.5	1000 PCS
5	10.0	15.0	1000 PCS
6	12.5	17.5	1000 PCS
7	15.0	20.0	1000 PCS
8	17.5	22.5	1000 PCS
9	20.0	25.0	500 PCS
10	22.5	27.5	500 PCS
11	25.0	30.0	500 PCS
12	27.5	32.5	500 PCS
13	30.0	35.0	500 PCS
14	32.5	37.5	500 PCS
15	35.0	40.0	500 PCS

A

B

C

D

E

F

Applicable P.C.B Thickness: 1.6mm

PIN Material : Brass
 Surface treatment: Tin plating
 Material: PA66 UL94 V-0+GF 25%

G

H

RoHS
Compliant

HSM 玄茂科技股份有限公司
HSUAN MAO TECHNOLOGY CO., LTD.

APPD. 核准
 DWG. 製圖 **HELEN**
 DATE 制表日
 2008/8/29

TOLERANCE 容許公差
 0 ±
 .00 ±
 ANG. ±
 SCALE 比例 參考
 UNIT 單位 M M
 PAGE 張數 1 OF 1
 REV. 版本 A

PART NAME 品名
 2.5mm WAFER XXP 180° TIN PLATING
 WHITE INSULATOR ROHS LOW-LDAD
 PART NO.
 料號 W2550-XXPSTW00R

G

H

1

2

3

4

5

6

7

8